

	Hits	Search Text	DBs
1	6317	(produc\$4 or mak\$3 or manufactur\$3) near20 ((IC or chip) adj12 card\$1)	USPAT; EPO; JPO; DERWENT;
2	6	(produc\$4 or mak\$3 or manufactur\$3) near20 ((IC or chip) adj12 card\$1) near20 (core or recess) near20 seal\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB
3	173	(produc\$4 or mak\$3 or manufactur\$3) near20 ((IC or chip) adj12 card\$1) near20 (core or recess)	USPAT; EPO; JPO; DERWENT; IBM_TDB
4	84	((protec\$4 near10 layer\$1) same card\$1) and 235/488.ccls.	USPAT; EPO; JPO; DERWENT;
5	138	((IC or chip) same card\$1) and 235/488.ccls.	USPAT; EPO; JPO; DERWENT;
6	32	((((IC or chip) same card\$1) and 235/488.ccls.) and paper	USPAT; EPO; JPO; DERWENT;
7	13	("4736966" "4868373" "4994659" "5033774" "5083850" "5138604" "5198652" "5244840" "5567362" "5760961" "5763868" "5888624" "6090471").PN.	USPAT
8	0	6575371.URPN.	USPAT
9	13	(card same chip same damag\$3) and 235/488.ccls.	USPAT; EPO; JPO; DERWENT;
10	6	("4065197" "4216577" "4288841" "4437718" "4447716" "4649418").PN.	USPAT
11	40	4727246.URPN.	USPAT
12	190	(core near40 (layer\$3 or substrate\$1)) near40 (data or chip or IC or smart) near20 card	USPAT; EPO; JPO; DERWENT;
13	28	((core near40 (layer\$3 or substrate\$1)) near40 (data or chip or IC or smart) near20 card) and 235/\$7.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB
14	4	6478228.URPN.	USPAT
15	4	6478228.URPN.	USPAT
16	3	("5321240" "5581445" "5955723").PN.	USPAT
17	8	((((core near40 (layer\$3 or substrate\$1)) near40 (data or chip or IC or smart) near20 card) and 235/\$7.ccls.) and paper	USPAT; EPO; JPO; DERWENT; IBM_TDB
18	7	((core near40 (layer\$3 or substrate\$1)) near40 (data or chip or IC or smart) near20 card) near30 paper	USPAT; EPO; JPO; DERWENT; IBM_TDB
19	5	("2932913" "3391479" "3457661" "4092234" "4269915").PN.	USPAT
20	24	4304809.URPN.	USPAT
21	29273	microporous	USPAT; EPO; JPO; DERWENT;

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22	1	microporous and 235/488.ccls.	USPAT; EPO; JPO; DERWENT;
23	5	microporous and 235/\$7.ccls..	USPAT; EPO; JPO; DERWENT;
24	92	gelatin\$1 and 235/\$7.ccls.	USPAT; EPO; JPO; DERWENT;
25	0	(core near40 image near40 photographi\$3 near40 layer\$1) and 235/\$7.ccls.	USPAT; EPO; JPO; DERWENT;
26	105	(core near40 image near40 photographi\$3 near40 layer\$1)	USPAT; EPO; JPO; DERWENT;
27	6	(core near40 image near40 photographi\$3 near40 layer\$1) near40 card\$1	USPAT; EPO; JPO; DERWENT;
28	47	(core near40 image near40 layer\$1) near40 card\$1	USPAT; EPO; JPO; DERWENT;
29	0	(core near40 image near40 photographi\$3 near40 layer\$1) near40 weld\$3	USPAT; EPO; JPO; DERWENT;
30	1	(core near40 (layer\$3 or substrate\$1)) near40 (data or chip or IC or smart) near20 card near40 weld\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB
31	2	("5842722").PN.	USPAT; EPO; JPO; DERWENT;
32	2	("4457798").PN.	USPAT; EPO; JPO; DERWENT;